

ABSTRACT**ELECTROLESS GOLD PLATED ELECTRONIC
COMPONENTS AND METHOD OF PRODUCING THE SAME**

An neutral electroless gold plating method that minimises "black band" corrosion problem in the final product. The electroless gold plating solution is provided at neutral pH in the presence of a reducing agent, a complexing agent and an accelerator to allow a gold layer of the desired thickness to be plated under manufacturing conditions. The gold layer produced thereof has good bondability and solderability.

No Figure